

Product Summary

| $V_{(BR)DSS}$ | $R_{DS(ON)}$ max | I_D max $T_C = +25^\circ C$ |
|---------------|-------------------------------|----------------------------------|
| 80V | 16m Ω @ $V_{GS} = 10V$ | 35A |
| | 22m Ω @ $V_{GS} = 6V$ | 30A |

Description and Applications

This MOSFET has been designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

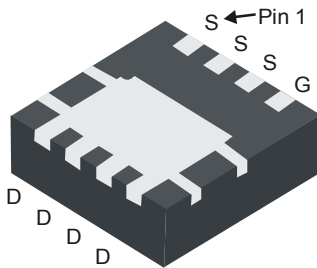
- Synchronous Rectifier
- Backlighting
- Power Management Functions
- DC-DC Converters

Features and Benefits

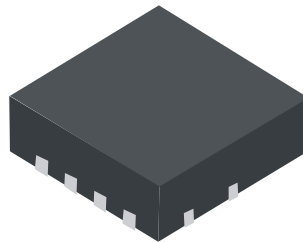
- Low $R_{DS(ON)}$ – ensures on state losses are minimized
- Excellent $Q_{gd} \times R_{DS(ON)}$ Product (FOM)
- Advanced Technology for DC/DC converts
- Small form factor thermally efficient package enables higher density end products
- Occupies just 33% of the board area occupied by SO-8 enabling smaller end product
- 100% UIS (Avalanche) rated
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

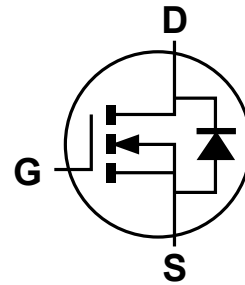
- Case: POWERDI[®]3333-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See diagram
- Terminals: Finish — Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.008 grams (approximate)



Bottom View



Top View



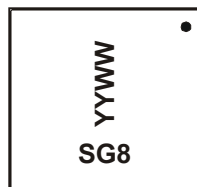
Equivalent Circuit

Ordering Information (Note 4)

| Part Number | Case | Packaging |
|---------------|---------------|-------------------|
| DMT8012LFG-7 | POWERDI3333-8 | 2,000/Tape & Reel |
| DMT8012LFG-13 | POWERDI3333-8 | 3,000/Tape & Reel |

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



SG8 = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Last digit of year (ex: 13 = 2013)
 WW = Week code (01 ~ 53)

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

| Characteristic | Symbol | Value | Units |
|--|--|------------|-------|
| Drain-Source Voltage | V_{DSS} | 80 | V |
| Gate-Source Voltage | V_{GSS} | ± 20 | V |
| Continuous Drain Current (Note 5) $V_{GS} = 10\text{V}$ | $T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$ | 9.5 7.6 | A |
| | $T_C = +25^\circ\text{C}$ $T_C = +70^\circ\text{C}$ | 35 28 | A |
| Maximum Continuous Body Diode Forward Current (Note 5) | I_S | 2 | A |
| Pulsed Drain Current (10 μs pulse, duty cycle = 1%) | I_{DM} | 80 | A |

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

| Characteristic | Symbol | Value | Units |
|--|-----------------|---------------------------|--------------------|
| Total Power Dissipation (Note 5) | P_D | $T_A = +25^\circ\text{C}$ | 2.2 |
| | | $T_C = +25^\circ\text{C}$ | 30 |
| Thermal Resistance, Junction to Ambient (Note 5) | $R_{\theta JA}$ | Steady State | 57 |
| | | $t < 10\text{s}$ | 35 |
| Thermal Resistance, Junction to Case (Note 5) | $R_{\theta JC}$ | 4.2 | $^\circ\text{C/W}$ |
| Operating and Storage Temperature Range | T_J, T_{STG} | -55 to 150 | $^\circ\text{C}$ |

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|--|--------------|-----|------|-----------|---------------|--|
| OFF CHARACTERISTICS (Note 6) | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | 80 | — | — | V | $V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$ |
| Zero Gate Voltage Drain Current | I_{DSS} | — | — | 1 | μA | $V_{DS} = 64\text{V}, V_{GS} = 0\text{V}$ |
| Gate-Source Leakage | I_{GSS} | — | — | ± 100 | nA | $V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$ |
| ON CHARACTERISTICS (Note 6) | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | 1 | 1.5 | 3 | V | $V_{DS} = V_{GS}, I_D = 250\mu\text{A}$ |
| Static Drain-Source On-Resistance | $R_{DS(on)}$ | — | 13 | 16 | m Ω | $V_{GS} = 10\text{V}, I_D = 12\text{A}$ |
| | | — | 14 | 22 | | $V_{GS} = 6\text{V}, I_D = 6\text{A}$ |
| Diode Forward Voltage | V_{SD} | — | 0.9 | 1.2 | V | $V_{GS} = 0\text{V}, I_S = 12\text{A}$ |
| DYNAMIC CHARACTERISTICS (Note 7) | | | | | | |
| Input Capacitance | C_{iss} | — | 1949 | — | pF | $V_{DS} = 40\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$ |
| Output Capacitance | C_{oss} | — | 177 | — | | |
| Reverse Transfer Capacitance | C_{rss} | — | 10 | — | | |
| Gate resistance | R_g | — | 0.7 | — | Ω | $V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$ |
| Total Gate Charge ($V_{GS} = 4.5\text{V}$) | Q_g | — | 15 | — | nC | $V_{DS} = 40\text{V}, I_D = 12\text{A}$ |
| Total Gate Charge ($V_{GS} = 10\text{V}$) | Q_g | — | 34 | — | | |
| Gate-Source Charge | Q_{gs} | — | 6 | — | | |
| Gate-Drain Charge | Q_{gd} | — | 4.5 | — | | |
| Turn-On Delay Time | $t_{D(on)}$ | — | 4.9 | — | nS | $V_{DD} = 40\text{V}, V_{GS} = 10\text{V}, I_D = 12\text{A}, R_G = 1.6\Omega,$ |
| Turn-On Rise Time | t_r | — | 3.8 | — | | |
| Turn-Off Delay Time | $t_{D(off)}$ | — | 16.5 | — | | |
| Turn-Off Fall Time | t_f | — | 3.5 | — | | |
| Body Diode Reverse Recovery Time | t_{rr} | — | 30.2 | — | nS | $I_F = 12\text{A}, di/dt = 100\text{A}/\mu\text{s}$ |
| Body Diode Reverse Recovery Charge | Q_{rr} | — | 34.6 | — | nC | |

- Notes:
- $R_{\theta JA}$ is determined with the device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to product testing.

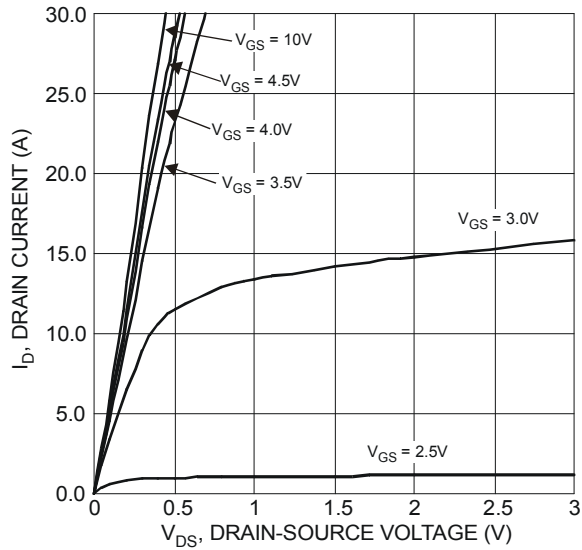


Figure 1 Typical Output Characteristics

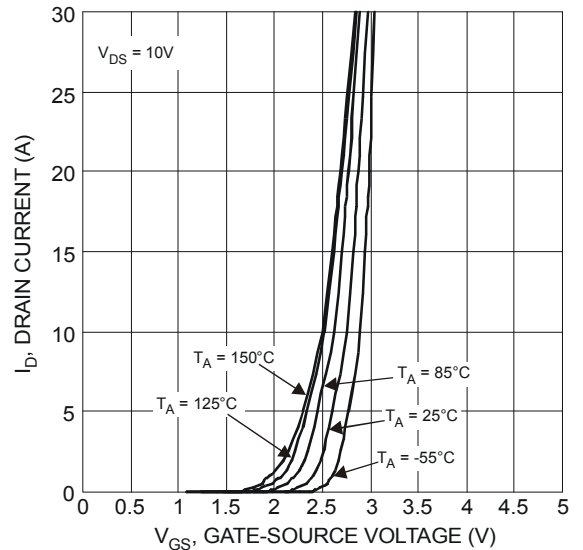


Figure 2 Typical Transfer Characteristics

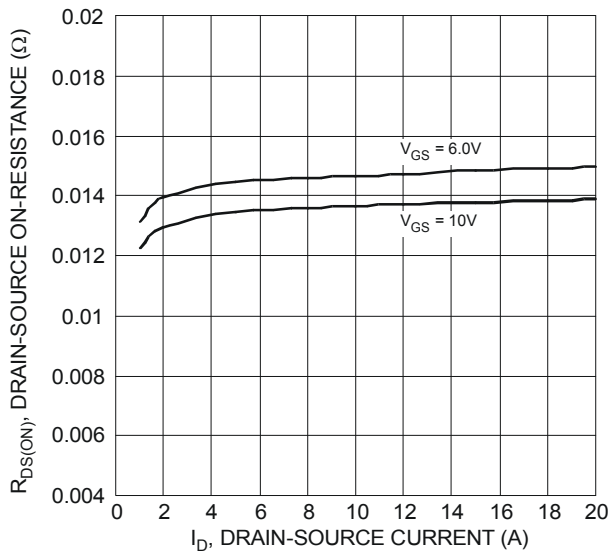


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

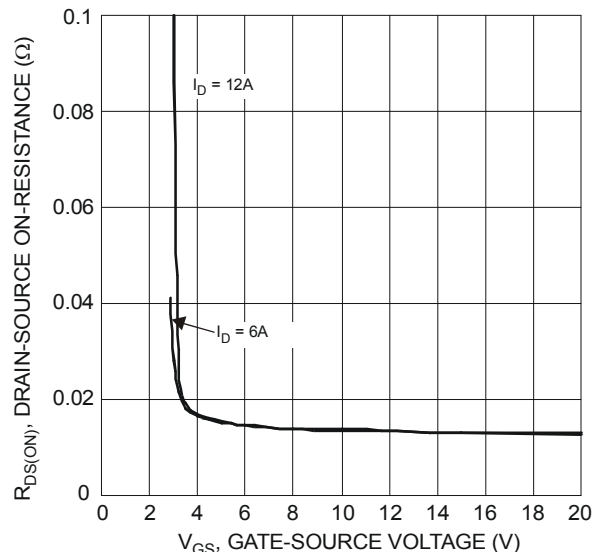


Figure 4 Typical Transfer Characteristics

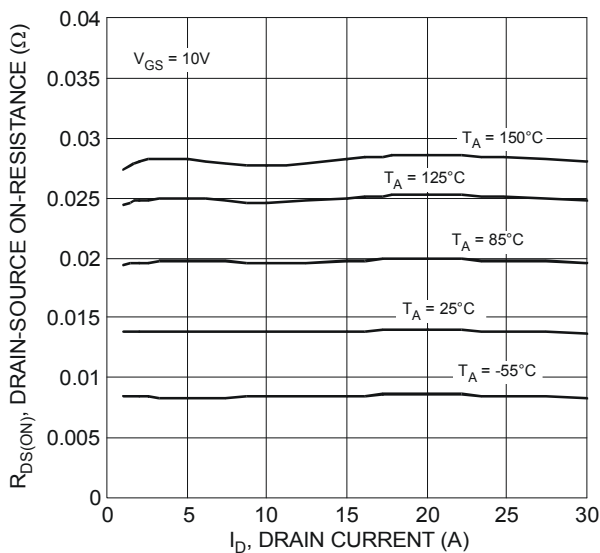


Figure 5 Typical On-Resistance vs. Drain Current and Temperature

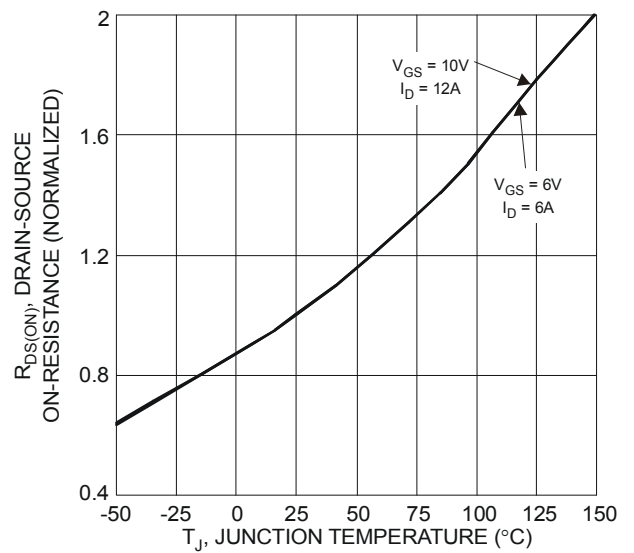


Figure 6 On-Resistance Variation with Temperature

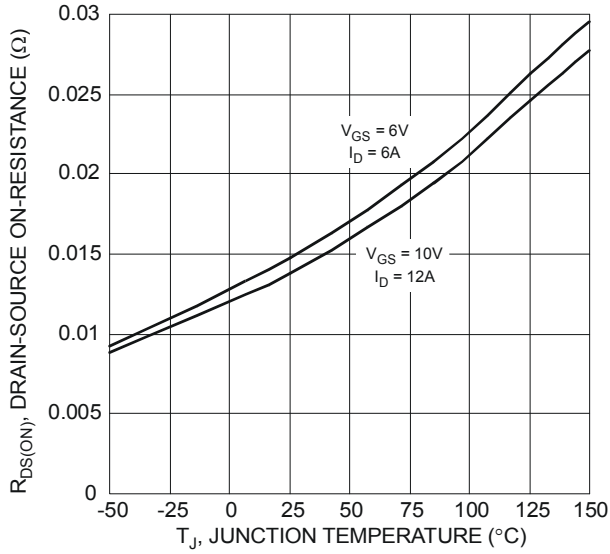


Figure 7 On-Resistance Variation with Temperature

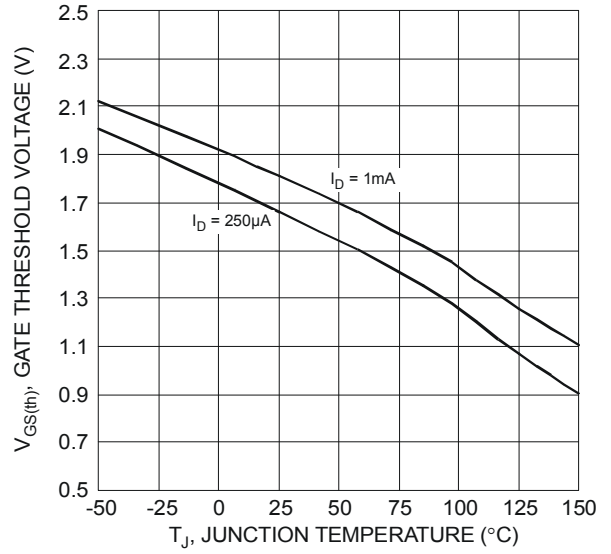


Figure 8 Gate Threshold Variation vs. Ambient Temperature

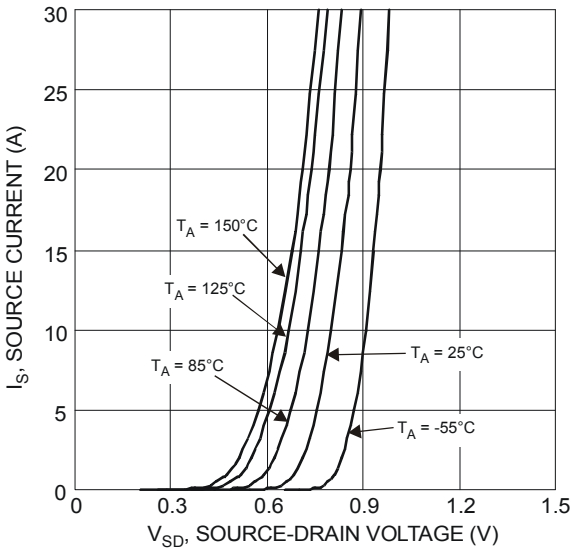


Figure 9 Diode Forward Voltage vs. Current

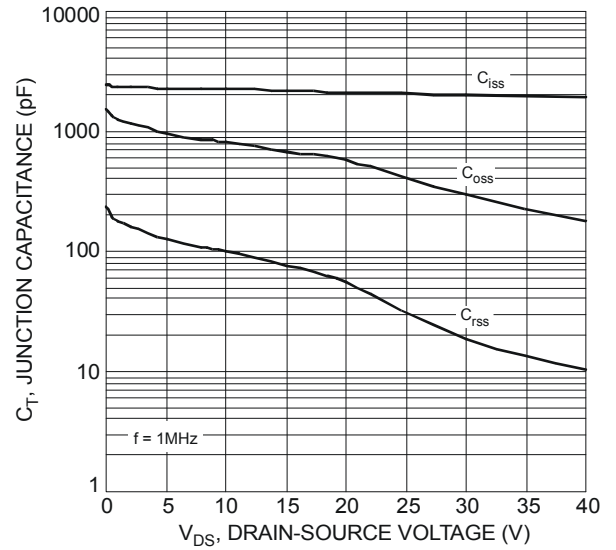


Figure 10 Typical Junction Capacitance

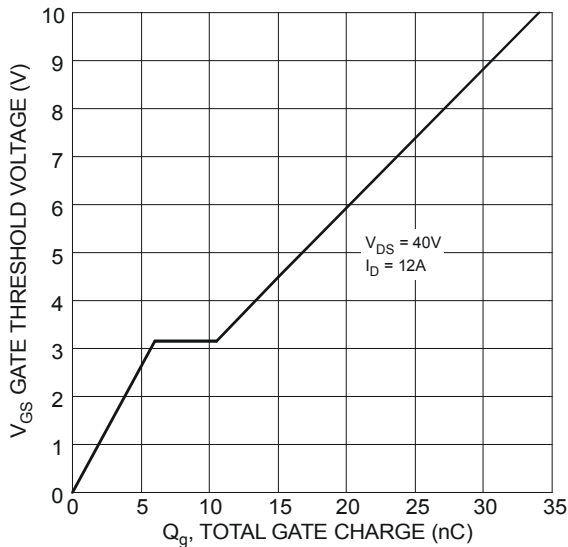


Figure 11 Gate Charge

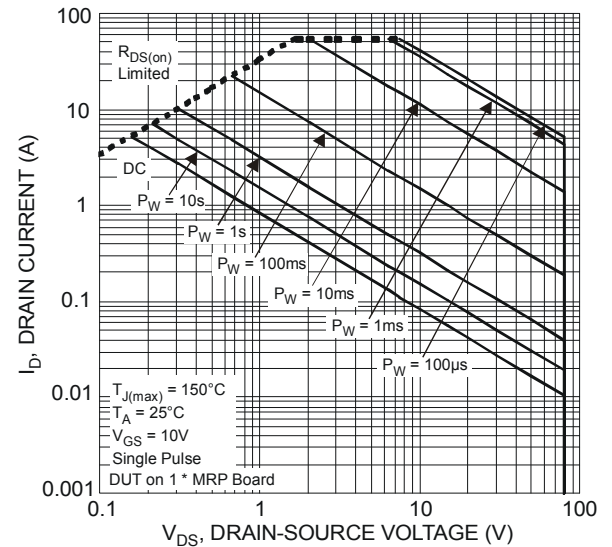


Figure 12 SOA, Safe Operation Area

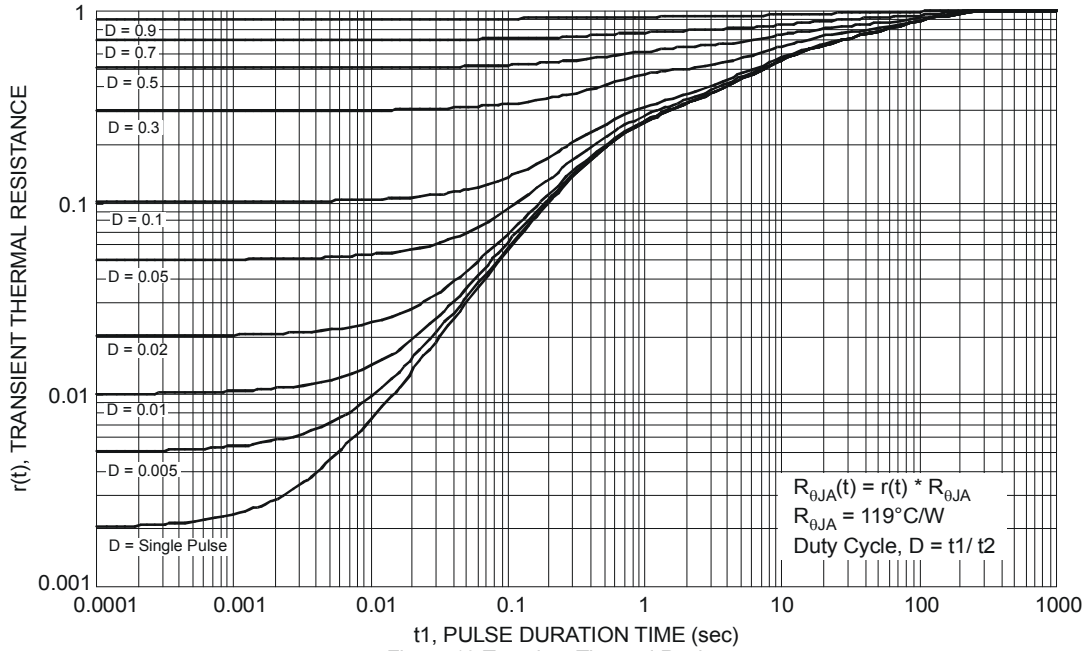
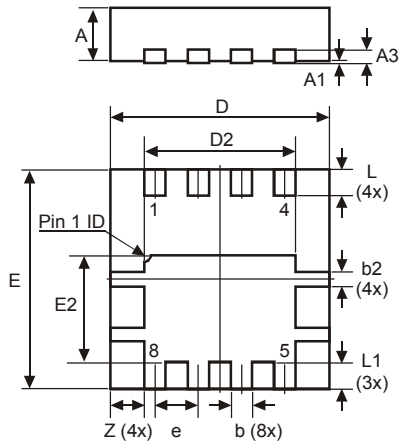


Figure 13 Transient Thermal Resistance

Package Outline Dimensions

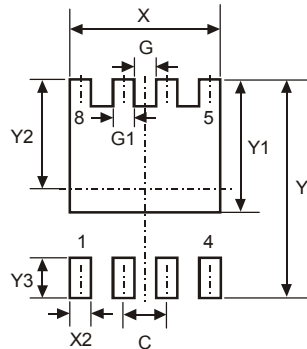
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



| POWERDI [®] 3333-8 | | | |
|-----------------------------|------|------|-------|
| Dim | Min | Max | Typ |
| D | 3.25 | 3.35 | 3.30 |
| E | 3.25 | 3.35 | 3.30 |
| D2 | 2.22 | 2.32 | 2.27 |
| E2 | 1.56 | 1.66 | 1.61 |
| A | 0.75 | 0.85 | 0.80 |
| A1 | 0 | 0.05 | 0.02 |
| A3 | - | - | 0.203 |
| b | 0.27 | 0.37 | 0.32 |
| b2 | - | - | 0.20 |
| L | 0.35 | 0.45 | 0.40 |
| L1 | - | - | 0.39 |
| e | - | - | 0.65 |
| Z | - | - | 0.515 |
| All Dimensions in mm | | | |

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| C | 0.650 |
| G | 0.230 |
| G1 | 0.420 |
| Y | 3.700 |
| Y1 | 2.250 |
| Y2 | 1.850 |
| Y3 | 0.700 |
| X | 2.370 |
| X2 | 0.420 |

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